

Polyphenylene sulfide

Fortron 4184L6 is an easier flow version of Fortron 4184L4. It offers similar characteristics to the 4184L4. This grade is especially used for thin walled parts requiring long flow lengths, stiffness and dimensional control. Applications made of this grade are typically electronic components.

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| i roduct imormation | | | |
|--|---------------------|----------|-----------------|
| Resin Identification | PPS-(GF+MD)5 | | ISO 1043 |
| Part Marking Code | >PPS-(GF+MD)5 | 3< | ISO 11469 |
| Rheological properties | | | |
| Moulding shrinkage, parallel | 0.3 | % | ISO 294-4, 2577 |
| Moulding shrinkage, normal | 0.6 | % | ISO 294-4, 2577 |
| Typical mechanical properties | | | |
| Tensile modulus | 16600 | MPa | ISO 527-1/-2 |
| Tensile stress at break, 5mm/min | 160 | MPa | ISO 527-1/-2 |
| Tensile strain at break, 5mm/min | 1.4 | % | ISO 527-1/-2 |
| Flexural modulus | 16200 | MPa | ISO 178 |
| Flexural strength | 250 | MPa | ISO 178 |
| Compressive modulus | 16200 | MPa | ISO 604 |
| Compressive strength | 245 | MPa | ISO 604 |
| Charpy impact strength, 23°C | 29 | kJ/m² | ISO 179/1eU |
| Charpy impact strength, -30°C | 29 | kJ/m² | ISO 179/1eU |
| Charpy notched impact strength, 23°C | | kJ/m² | ISO 179/1eA |
| Charpy notched impact strength, -30°C | | kJ/m² | ISO 179/1eA |
| Izod notched impact strength, 23°C | | kJ/m² | ISO 180/1A |
| Izod notched impact strength, -30°C | | kJ/m² | ISO 180/1A |
| Izod impact strength, 23°C | | kJ/m² | ISO 180/1U |
| Izod impact strength, -30°C | | kJ/m² | ISO 180/1U |
| Hardness, Rockwell, M-scale | 100 | | ISO 2039-2 |
| Poisson's ratio | 0.33 ^[C] | | |
| [C]: Calculated | | | |
| Thermal properties | | | |
| Melting temperature, 10°C/min | 280 | °C | ISO 11357-1/-3 |
| Glass transition temperature, 10°C/min | 90 | °C | ISO 11357-1/-3 |
| Temperature of deflection under load, 1.8 MPa | 270 | °C | ISO 75-1/-2 |
| Temperature of deflection under load, 8 MPa | 215 | °C | ISO 75-1/-2 |
| Coefficient of linear thermal expansion (CLTE), parallel | 24 | E-6/K | ISO 11359-1/-2 |
| Coefficient of linear thermal expansion (CLTE), normal | 32 | E-6/K | ISO 11359-1/-2 |
| Specific heat capacity of melt | 1500 | J/(kg K) | ISO 22007-4 |

Printed: 2024-09-05 Page: 1 of 14



Polyphenylene sulfide

Flammability

| Burning Behav. at 1.5mm nom. thickn. | V-0 class | IEC 60695-11-10 |
|--------------------------------------|-----------|-----------------|
| Thickness tested | 1.5 mm | IEC 60695-11-10 |
| Burning Behav. at thickness h | V-0 class | IEC 60695-11-10 |
| Thickness tested | 0.75 mm | IEC 60695-11-10 |

Electrical properties

| Relative permittivity, 1MHz | 4.7 | | IEC 62631-2-1 |
|-----------------------------|---------|-------|---------------|
| Dissipation factor, 1MHz | 20 E- | -4 | IEC 62631-2-1 |
| Volume resistivity | >1E13 O |)hm.m | IEC 62631-3-1 |
| Surface resistivity | >1E15 O |)hm | IEC 62631-3-2 |
| Electric strength | 27 k\ | V/mm | IEC 60243-1 |
| Comparative tracking index | 150 | | IEC 60112 |
| Arc Resistance | 156 s | | UL 746B |

Physical/Other properties

| Water absorption, 2mm | 0.02 % | Sim. to ISO 62 |
|---------------------------------|------------------------|----------------|
| Water absorption, Immersion 24h | 0.03 % | Sim. to ISO 62 |
| Density | 1800 kg/m ³ | ISO 1183 |

Injection

| Drying Recommended | yes | |
|---------------------------------|-----------|-----|
| Drying Temperature | 130 | °C |
| Drying Time, Dehumidified Dryer | 2 - 4 | h |
| Processing Moisture Content | ≤0.02 | % |
| Melt Temperature Optimum | 330 | °C |
| Min. melt temperature | 310 | °C |
| Max. melt temperature | 340 | °C |
| Screw tangential speed | 0.2 - 0.3 | m/s |
| Mold Temperature Optimum | 150 | °C |
| Min. mould temperature | 140 | °C |
| Max. mould temperature | 160 | °C |
| Hold pressure range | 30 - 70 | MPa |
| Back pressure | 3 | MPa |
| Ejection temperature | 217 | °C |

Characteristics

Additives Release agent

Additional information

Injection molding Preprocessing

Predrying in a dehumidified air dryer at 130 - 140 degC/3-4 hours is recommended.

Processing

Printed: 2024-09-05 Page: 2 of 14



Polyphenylene sulfide

On injection molding machines with 15-25 D long three-section screws, as are usual in the trade, the FORTRON is processable. A shut-off nozzle is preferred to a free-flow nozzle.

Melt temperature 320-340 degC Mold wall temperature at least 140 degC

A medium injection rate is normally preferred. All mold cavities must be effectively vented.

Postprocessing

Tool temperature of at least 135 degC is recommended for parts to achieve maximum crystallizable potential.

Processing Notes

Pre-Drying

FORTRON should in principle be predried. Because of the necessary low maximum residual moisture content the use of dry air dryers is recommended. The dew point should be =< - 30° C. The time between drying and processing should be as short as possible.

Storage

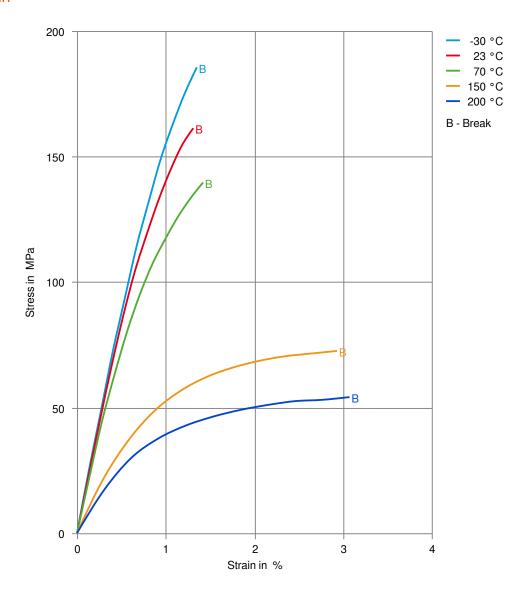
For subsequent storage the material should be stored dry in the dryer until processed (<= 60 h).

Printed: 2024-09-05 Page: 3 of 14



Polyphenylene sulfide

Stress-strain

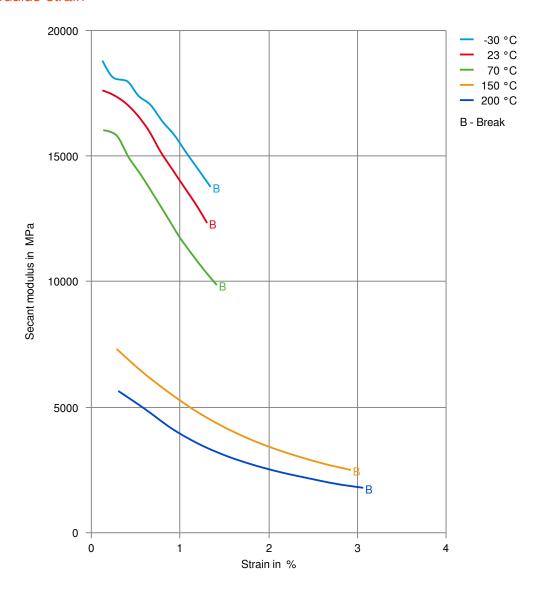


Printed: 2024-09-05 Page: 4 of 14



Polyphenylene sulfide

Secant modulus-strain

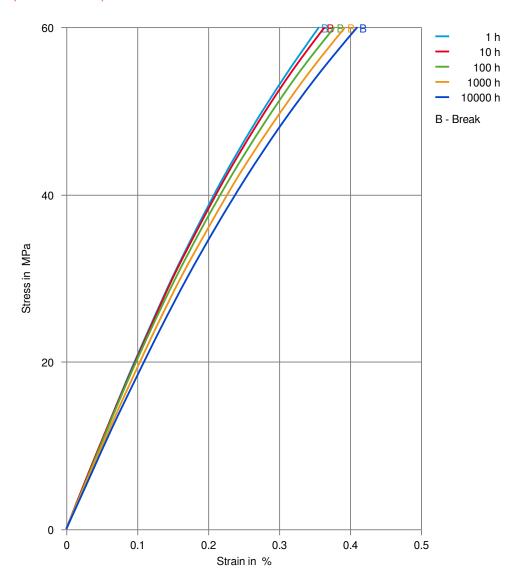


Printed: 2024-09-05 Page: 5 of 14



Polyphenylene sulfide

Stress-strain (isochronous) 23°C

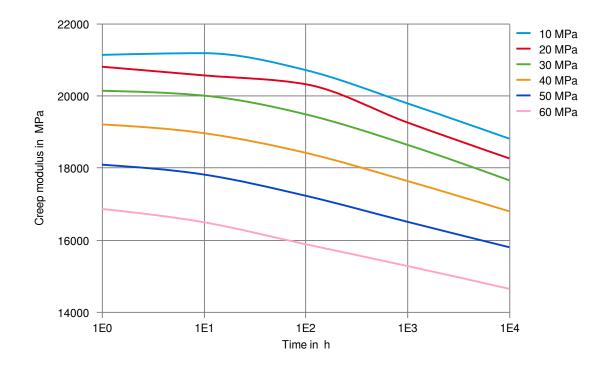


Printed: 2024-09-05 Page: 6 of 14



Polyphenylene sulfide

Creep modulus-time 23°C

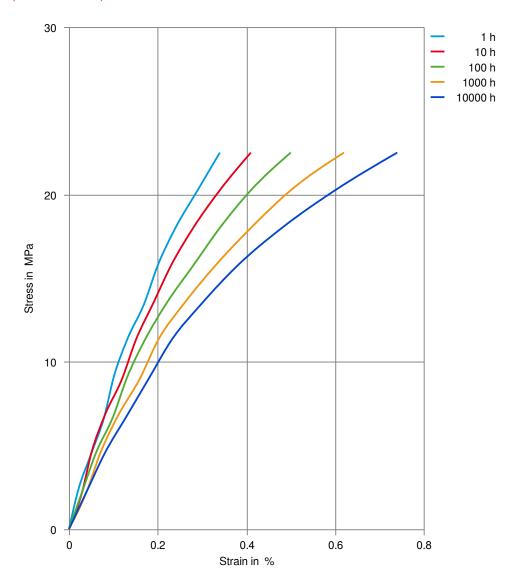


Printed: 2024-09-05 Page: 7 of 14



Polyphenylene sulfide

Stress-strain (isochronous) 120°C

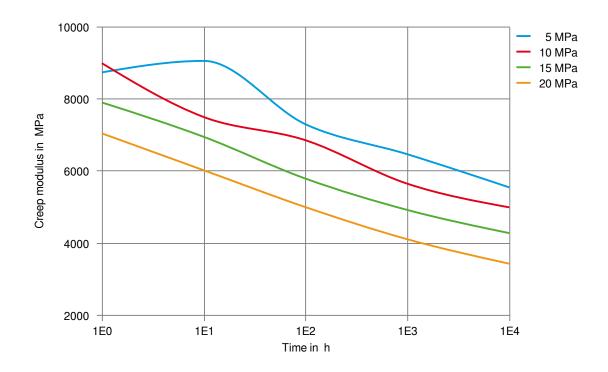


Printed: 2024-09-05 Page: 8 of 14



Polyphenylene sulfide

Creep modulus-time 120°C

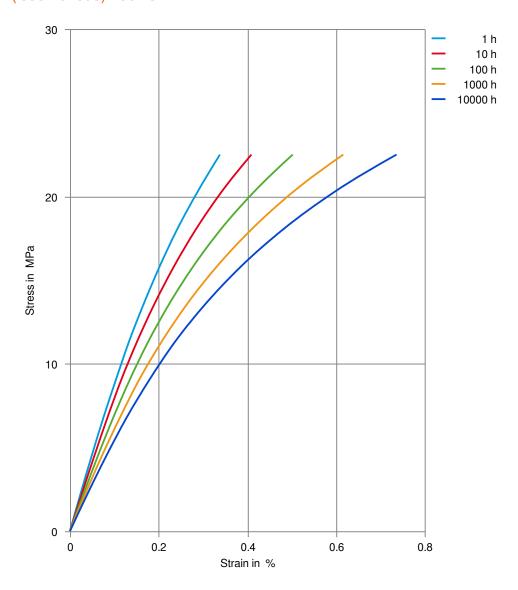


Printed: 2024-09-05 Page: 9 of 14



Polyphenylene sulfide

Stress-strain (isochronous) 150°C

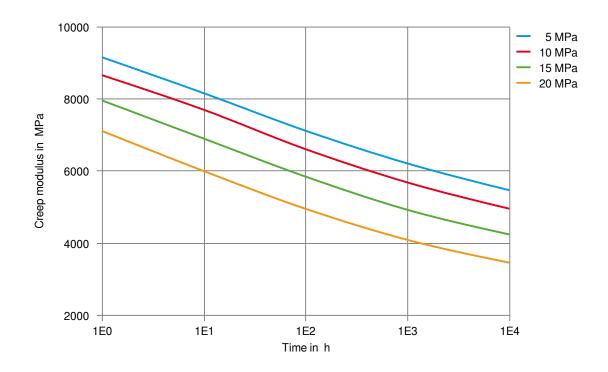


Printed: 2024-09-05 Page: 10 of 14



Polyphenylene sulfide

Creep modulus-time 150°C

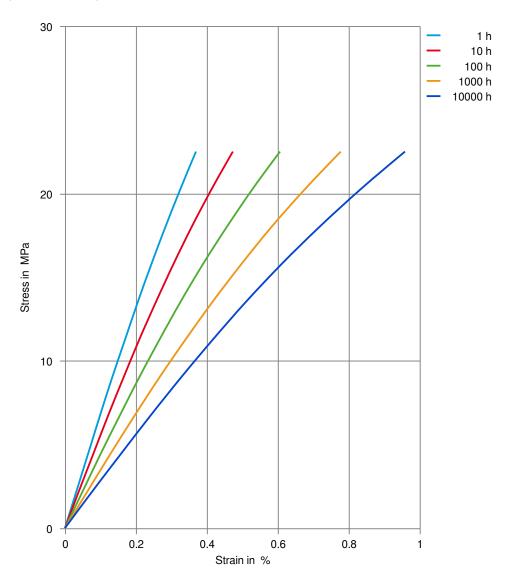


Printed: 2024-09-05 Page: 11 of 14



Polyphenylene sulfide

Stress-strain (isochronous) 200°C

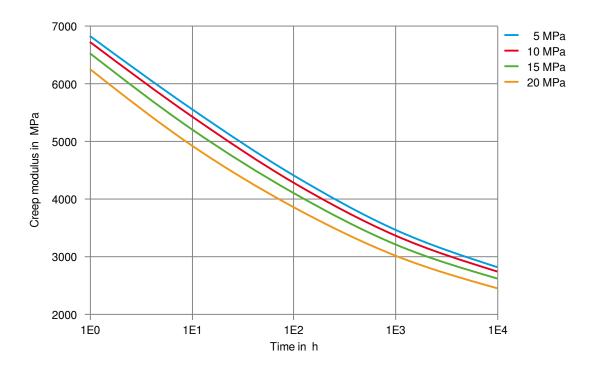


Printed: 2024-09-05 Page: 12 of 14



Polyphenylene sulfide

Creep modulus-time 200°C

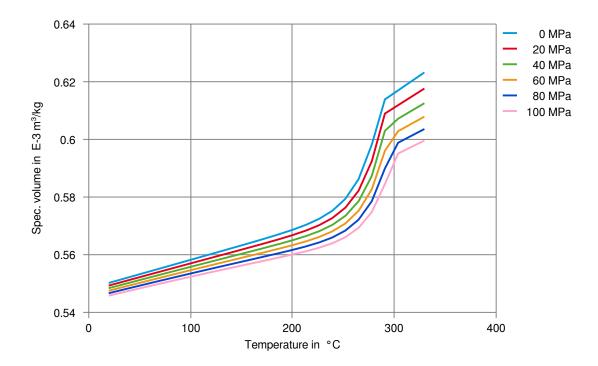


Printed: 2024-09-05 Page: 13 of 14



Polyphenylene sulfide

Specific volume-temperature (pvT)



Printed: 2024-09-05 Page: 14 of 14

Revised: 2024-06-13 Source: Celanese Materials Database

NOTICE TO USERS: Values shown are based on testing of laboratory test specimens and represent data that fall within the standard range of properties for natural material. These values alone do not represent a sufficient basis for any part design and are not intended for use in establishing maximum, minimum, or ranges of values for specification purposes. Colourants or other additives may cause significant variations in data values. Properties of moulded parts can be influenced by a wide variety of factors including, but not limited to, material selection, additives, part design, processing conditions and environmental exposure. Other than those products expressly identified as medical grade (including by MT® product designation or otherwise), Celanese's products are not intended for use in medical or dental implants. Regardless of any such product designation, any determination of the suitability of a particular material and part design for any use contemplated by the users and the manner of such use is the sole responsibility of the users, who must assure themselves that the material as subsequently processed meets the needs of their particular product or use. To the best of our knowledge, the information contained in this publication is accurate; however, we do not assume any liability whatsoever for the accuracy and completeness of such information. The information contained in this publication should not be construed as a promise or guarantee of specific properties of our products. It is the sole responsibility of the users to investigate whether any existing patents are infringed by the use of the materials mentioned in this publication. Moreover, there is a need to reduce human exposure to many materials to the lowest practical limits in view of possible adverse effects. To the extent that any hazards may have been mentioned in this publication, we neither suggest nor guarantee that such hazards are the only ones that exist. We recommend that persons intending to rely on any recommendation or to use any e

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